



Click [here](#) for the 3D model.

#### General Information

|                          |  |
|--------------------------|--|
| Series                   | CBR-SMD RF COG                                 |
| Style                    | SMD Chip                                       |
| Description              | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features                 | Ultra High Q, Low ESR, Class I                 |
| RoHS                     | Yes  |
| Termination              | Tin  |
| Marking                  | false  |
| AEC-Q200                 | No   |
| Typical Component Weight | 5.29 mg  |
| Notes                    | Solder Wave or Solder Reflow.                  |
| Shelf Life               | 78 Weeks                                       |
| MSL                      | 1  |

#### Dimensions

|           |                 |
|-----------|-----------------|
| Chip Size | 0603            |
| L         | 1.6mm +/-0.1mm  |
| W         | 0.8mm +/-0.1mm  |
| T         | 0.8mm +/-0.07mm |
| B         | 0.4mm +/-0.15mm |

#### Packaging Specifications

|                    |                          |
|--------------------|--------------------------|
| Packaging          | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 4000                     |

#### Specifications

|                                 |                     |
|---------------------------------|---------------------|
| Capacitance                     | 4 pF                |
| Capacitance Tolerance           | +/-0.25 pF          |
| Voltage DC                      | 50 VDC              |
| Dielectric Withstanding Voltage | 125 VDC             |
| Temperature Range               | -55/+125°C          |
| Temperature Coefficient         | COG                 |
| Dissipation Factor              | 0.208%              |
| Aging Rate                      | 0% Loss/Decade Hour |
| Insulation Resistance           | 10 GOhms            |
| Quality Factor                  | 480                 |